



# Qualcomm® Cloud AI 100

**Purpose-built for  
high performance,  
low-power  
AI processing in  
the cloud and edge.**



Dual M.2

PCIe

Form Factor	HHHL-Pro	HHHL-Std	HHHL-Lite	Dual M.2	Dual M.2e
Power (TDP)	75 W	75 W	35, 45, 55 W (Configurable)	15 W – 25 W	15 W – 25 W
ML Capacity (INT8)	Up to 400 TOPS	Up to 350 TOPS	Up to 137 TOPS	Up to 200 TOPS	Up to 70 TOPS
On-Die SRAM	144 MB	126 MB	81 MB	126 MB	81 MB
On-Card DRAM	32 GB LPR4x 137 GB/s	16 GB LPR4x 137 GB/s	16 GB LPR4x 137 GB/s	16 GB LPR4x 137 GB/s	8 GB LPR4x 68 GB/s
Host Interface	PCIe Gen 4 8 lanes	PCIe Gen 4 8 lanes	PCIe Gen 4 8 lanes	PCIe Gen 3 4 lanes	PCIe Gen 3 4 lanes